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PATENT  
Attorney Docket No.: AM524R1/T28900  
TTC No.: 16301-028900

Assistant Commissioner for Patents  
Washington, D.C. 20231

On Dec. 16, 1999

TOWNSEND and TOWNSEND and CREW LLP

By: Lynda Reisch

8/a  
1-12-00  
M.R.

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

KATSUYUKI MUSAKA et al.

Application No.: 09/187,551

Filed: November 5, 1998

For: METHOD FOR FORMING A THIN  
FILM FOR A SEMICONDUCTOR  
DEVICE

Examiner: Marianne Padgett

Art Unit: 1762

AMENDMENT

RECEIVED  
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Assistant Commissioner for Patents  
Washington, D.C. 20231

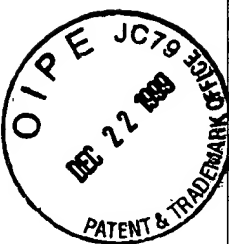
Sir:

In response to the Office Action mailed July 16, 1999, please amend the above-identified application as follows:

IN THE CLAIMS:

✓✓  
Please cancel claims 11-26 without prejudice; amend claims 1 and 8; and add new claims 27-34. Note that the remaining claims are unamended but are reproduced below for the Examiner's convenience and reference.

1. (Amended) A method of forming a conformal thin film of silicon oxide on a substrate having spaced conductive lines thereon comprising the steps of:  
mounting a substrate onto a substrate support in a vacuum chamber;  
forming a plasma in the vacuum chamber in a region above the substrate by means of an electrical power source from a reaction gas comprising a mixture of

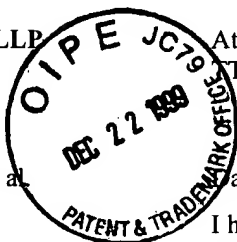


Q-

Amendment Transmittal

GP 1762/8

**TOWNSEND and TOWNSEND and CREW LLP**  
(650) 326-2400



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TTC No. 16301-028900

In re application of: KATSUYUKI MUSAKA et al.

Date: December 16, 1999

Application No.: 09/187,551

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Group Art Unit: 1762

For: METHOD FOR FORMING A THIN FILM FOR  
A SEMICONDUCTOR DEVICE

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Washington, D.C. 20231

**THE ASSISTANT COMMISSIONER FOR PATENTS**  
Washington, D.C. 20231

Signed: *Lynda Poltsch*

Sir:

Transmitted herewith is an Amendment in the above-identified application. Also enclosed are:

- ☒ Petition to Extend Time to Respond
- ☒ Return Postcard.

The filing fee has been calculated as shown below:

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	CLAIMS REMAINING AFTER AMENDMENT		HIGHEST NO. PREVIOUSLY PAID FOR	PRESENT EXTRA
TOTAL	* 18	MINUS	** 26	= 0
INDEP.	* 3	MINUS	*** 5	= 0
[ ] FIRST PRESENTATION OF MULTIPLE DEP. CLAIM				

SMALL ENTITY

RATE	ADDIT. FEE
x \$9.00 =	
x \$39.00 =	
+ \$130.00 =	
TOTAL	

OTHER THAN  
SMALL ENTITY

RATE	ADDIT. FEE
x \$18.00 =	\$0.00
x \$78.00 =	\$0.00
+ \$260.00 =	
TOTAL	\$0.00

Please charge Deposit Account No. 20-1430 as follows:

- ☒ Claims fee \$ 0.00
- ☒ Any additional fees associated with this paper or during the pendency of this application.

No extra copies of this sheet are enclosed.

TOWNSEND and TOWNSEND and CREW LLP

*Chun-Pok Leung*  
Chun-Pok Leung, Reg. No. 41,405  
Attorneys for Applicant